Vishay Siliconix

RoHS

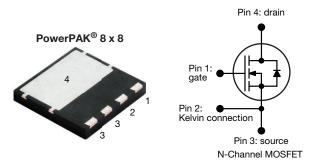
COMPLIANT

HALOGEN

FREE GREEN

(5-2008)

E Series Power MOSFET with Fast Body Diode



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650)			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V 0.161				
Q _g max. (nC)	86	i			
Q _{gs} (nC)	13				
Q _{gd} (nC)	23				
Configuration	Single				

FEATURES

- Completely lead (Pb)-free device
- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH21N60EF-T1-GE3

ABSOLUTE MAXIMUM RATINGS	$T_C = 25 ^{\circ}C$, un	less otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	600	V
Gate-source voltage			V_{GS}	± 30	v
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$,	19	А
	V _{GS} at 10 V	T _C = 100 °C	I _D	12	
Pulsed drain current ^a			I _{DM}	47	
Linear derating factor				1.4	W/°C
Single pulse avalanche energy b			E _{AS}	226	mJ
Maximum power dissipation			P_{D}	174	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope T _J = 125 °C			dV/dt	70	1//22
Reverse diode dV/dt ^c				20	V/ns

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. $V_{DD} = 50 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 28.2 \,^{\circ}\text{mH}$, $R_g = 25 \,^{\circ}\Omega$, $I_{AS} = 4 \,^{\circ}\text{A}$
- c. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	40	52	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	0.55	0.72	C/VV	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 10 mA	-	0.63	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Octo Corres Laslana		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-Source Leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zana Oata Valtana Busin Ormant		V _{DS} =	V _{DS} = 480 V, V _{GS} = 0 V		-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	100	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11 A	-	0.161	0.185	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D = 11 A	-	7.3	-	S
Dynamic				•	•	•	
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,	-	2035	-	
Output Capacitance	C _{oss}	,	V _{DS} = 100 V,	_	96	-	
Reverse Transfer Capacitance	C_{rss}		f = 1 MHz	_	6	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	., .,	//. 400 // // O //	-	60	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$V_{DS} = 0$	/ to 480 V, V _{GS} = 0 V	-	257	-	
Total Gate Charge	Qg			-	57	86	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 11 \text{ A}, V_{DS} = 480 \text{ V}$	-	13	-	nC
Gate-Drain Charge	Q _{gd}			-	23	-	
Turn-On Delay Time	t _{d(on)}			-	20	40	
Rise Time	t _r	V _{DD} =	: 480 V, I _D = 11 A,	-	43	86	
Turn-Off Delay Time	t _{d(off)}		$= 10 \text{ V}, R_g = 9.1 \Omega$	-	65	98	ns
Fall Time	t _f			-	43	86	
Gate Input Resistance	R_g	f = 1	MHz, open drain	0.25	0.8	1.0	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the		-	-	19	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	47	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C	C, I _S = 11 A, V _{GS} = 0 V	-	0.9	1.2	V
Reverse Recovery Time	t _{rr}			-	137	274	ns
Reverse Recovery Charge	Q _{rr}		5 °C, I _F = I _S = 11 A,	-	0.8	1.6	μC
Reverse Recovery Current	I _{RRM}		100 A/ μ s, V _R = 25 V	_	12	-	A

Notes

- d. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}
- e. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

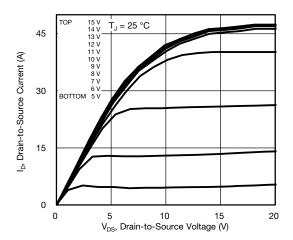


Fig. 1 - Typical Output Characteristics

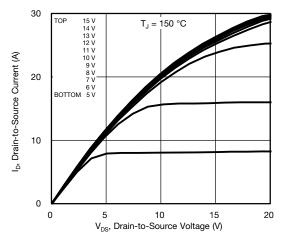


Fig. 2 - Typical Output Characteristics

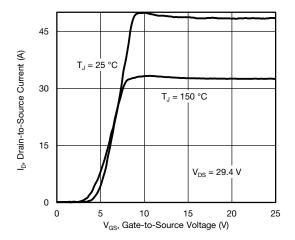


Fig. 3 - Typical Transfer Characteristics

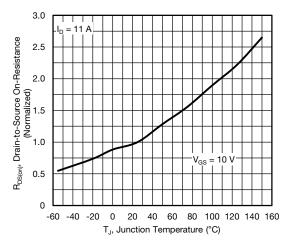


Fig. 4 - Normalized On-Resistance vs. Temperature

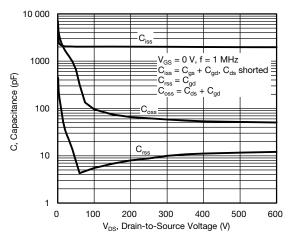


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

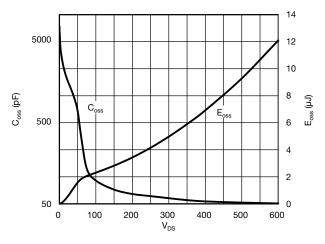


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}



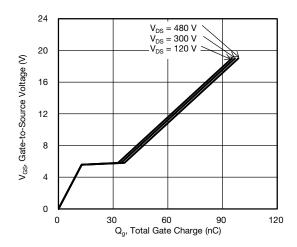


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

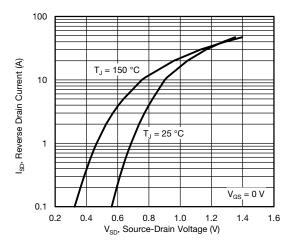


Fig. 8 - Typical Source-Drain Diode Forward Voltage

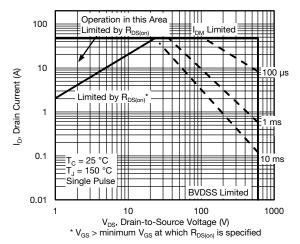


Fig. 9 - Maximum Safe Operating Area

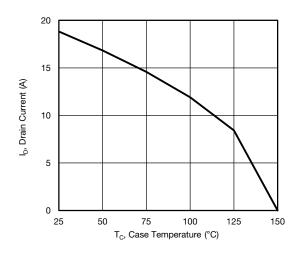


Fig. 10 - Maximum Drain Current vs. Case Temperature

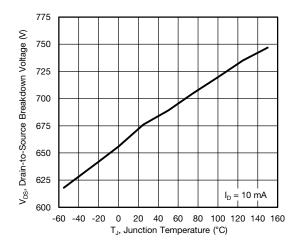


Fig. 11 - Temperature vs. Drain-to-Source Voltage



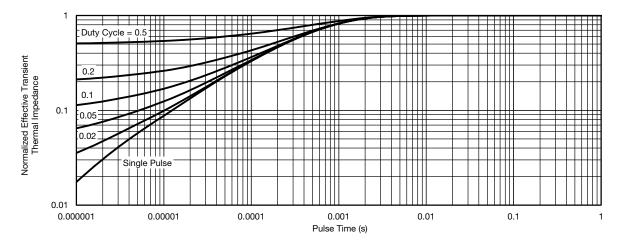


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

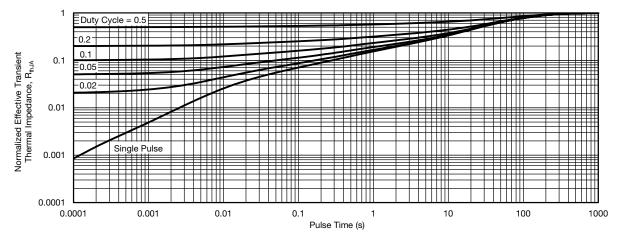


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

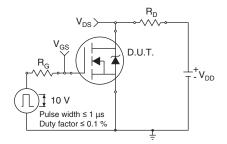


Fig. 14 - Switching Time Test Circuit

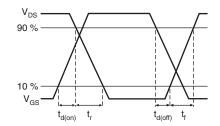


Fig. 15 - Switching Time Waveforms



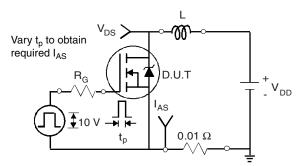


Fig. 16 - Unclamped Inductive Test Circuit

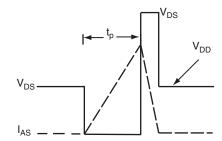


Fig. 17 - Unclamped Inductive Waveforms

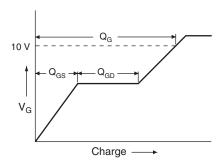


Fig. 18 - Basic Gate Charge Waveform

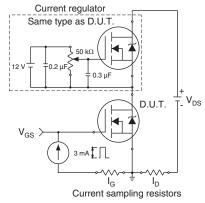
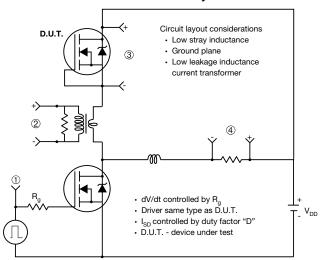


Fig. 19 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



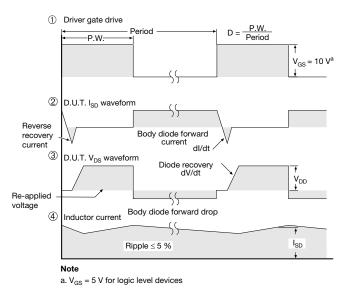


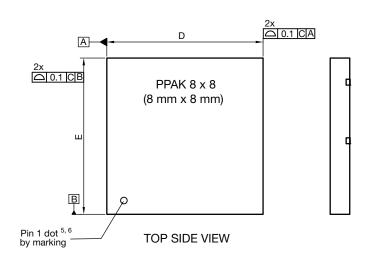
Fig. 20 - For N-Channel

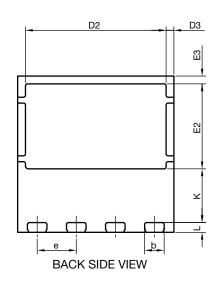
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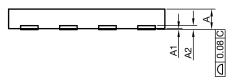


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PowerPAK® 8 x 8 Case Outline







DIM.	MILLIMETERS			INCHES		
DIIVI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Α	0.95	1.00	1.05	0.037	0.039	0.041
A1	0.00	-	0.05	0.000	-	0.002
A2	020 ref.				0.008 ref.	
b	0.95	1.00	1.05	0.037	0.039	0.041
D	7.90	8.00	8.10	0.311	0.315	0.319
D2	7.10	7.20	7.30	0.280	0.283	0.287
D3	0.40 BSC			0.016 BSC		
е	2.00 BSC		0.079 BSC			
E	7.90	8.00	8.10	0.311	0.315	0.319
E2	4.30	4.35	4.40	0.169	0.171	0.173
E3	0.40 BSC			0.40 BSC 0.016 BSC		
K	2.75 BSC		0.108 BSC			
L	0.45	0.50	0.55	0.018	0.020	0.022
N ⁽³⁾	8				8	

Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

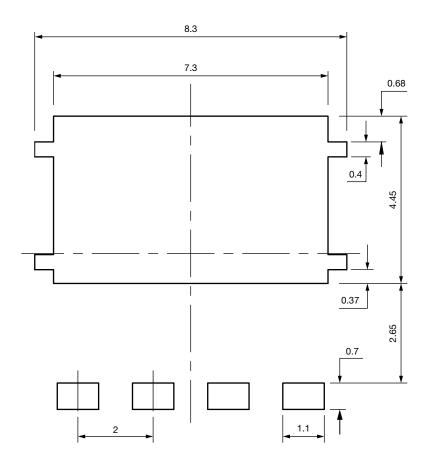
ECN: E20-0518-Rev. B, 28-Sep-2020

DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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